

ABSTRACT

The invention is directed to a fluxing curative for curing an underfill that comprises an epoxy resin and for fluxing a solder during a solder assembly of an electronic component to an electronic device substrate and a method for producing the fluxing curative. Specifically, the fluxing curative comprises a salt that is a reaction product of an imidazole component and a carboxylic acid component having at least 10 carbon atoms per molecule. Additionally, the invention is directed to an underfill solution comprising the fluxing curative and a method of attaching an integrated circuit device using the underfill solution.